

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Wood et al.

Patent No.: 6,036,872
Serial No.: 09/052,645

Examiner: N. Nguyen

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Group Art Unit: 1763

For: METHOD OF MAKING A WAFER-PAIR HAVING SEALED CHAMBERS

Docket No.: 1100.1138101 (H16-17400)

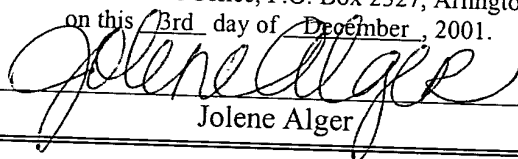
PRELIMINARY AMENDMENT

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By


Jolene Alger

Sir:

Please amend the above-captioned application as follows:

In the Claims

Please add newly presented claims 25-55 as follows:

25. A method for making a wafer-pair having deposited layer plugged sealed chambers, comprising:

growing a thermal layer on a first side of a first wafer;

depositing a nitride layer on the thermal layer;

depositing, patterning and removing portions of first metal layer on the nitride

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